

<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No. NSC1P296/P05887	Application No.: <del>NEW</del> 101826755
	Applicant: Soon et al.	Group 2811
	Filing Date 4/15/04	<del>UNASSIGNED</del>
	HEREWITH	

### U.S. Patent and Published Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
DHO	A1	5,328,079	07/12/1994	Mathew et al.	11	11	
	A2	5,408,127	4/18/95	Mostafazadeh	11	11	
	A3	4,818,895	4/4/89	Kaufman	11	11	
	A4	5,735,030	4/7/98	Orcutt	11	11	
	A5	6,399,421	06/02	Han et al.	11	11	
	A6	5,463,253	10/95	Waki et al.	11	11	
	A7	6,437,429	08/02	Wu et al.	11	11	
	A8	6,118,184	09/00	Ishio et al.	11	11	
	A9	5,471,369	11/95	Honda et al.	11	11	
	A10	2002/0137327	09/02	Arakawa	11	11	
DHO	A11	5,545,922	08/96	Golwalker et al.	11	11	
	A12	6,353,265	03/02	Michii	11	11	

### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
DHO	B1	WO02/08257	10/17/02	WIPO	11	11		
	B2	EP0753891	1/15/97	EPO	11	11		

### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DHO	C1	John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
DHO	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: <a href="http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm">http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm</a> , on March 16, 2004, 25 Pages
DHO	C3	Prof. Daniel F. Baldwin, "Fundamentals of IC Assembly," McGraw-Hill, Chapter. 9, pages 342-353, 2001
DHO	C4	Semiconductor Packaging Assembly Technology, printed from <a href="http://www.national.com">www.national.com</a> , 8 pages, 1999

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OK	C5	Nakanishi et al., "Development of High Density Memory IC Package by Stacking IC Chips," Abstract No. XP000624986, IEEE, Vol. Conf. 45, Pages 634-640 (1995)
OK	C6	Patent Abstract of Japan, Pub No. 63219131, Pub Date 9/12/88, 2 Pages
Examiner	Date Considered 1/11/05 <i>Ralph H. Orr</i>	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.